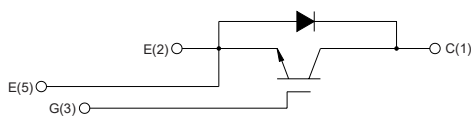


SGO400NF120UC3

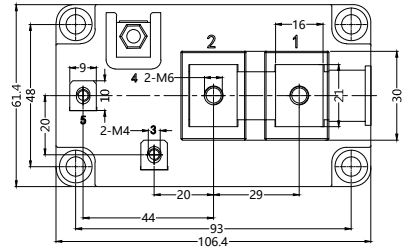
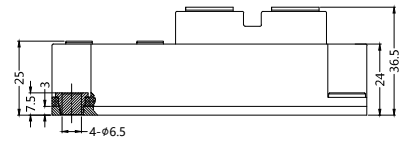
IGBT Modules



SGO400NF120UC3



Dimensions in mm (1mm = 0.0394")



$T_c = 25^{\circ}\text{C}$, unless otherwise specified

Symbol	Conditions	Values	Units
IGBT			
V_{CES}		1200	V
I_{Cnom}		400	A
I_{CRM}	$T_c = 25^{\circ}\text{C}$, $t_p = 1\text{ms}$	1200	A
V_{GES}		± 20	V
T_{vj}		$-40 \dots +175$	$^{\circ}\text{C}$
Inverse Diode			
I_F	$T_c = 25(80)^{\circ}\text{C}$	440(330)	A
I_{FRM}	$T_c = 25^{\circ}\text{C}$, $t_p = 1\text{ms}$	1200	A
I_{FSM}	$t_p = 10\text{ms}$; sin.; $T_j = 150^{\circ}\text{C}$	1980	A
Module			
$I_t(\text{RMS})$	$T_{terminal} = 80^{\circ}\text{C}$	500	A
T_{stg}		$-40 \sim 125$	$^{\circ}\text{C}$
V_{Isol}	AC, 1min	4000	V

Features

- Planar Gate Field Stop IGBT technology
- Low switching losses
- Switching frequency $> 20\text{kHz}$
- Square RBSOA, no latch up
- High short circuit capability
- Positive temperature coefficient for easy parallelling
- MOS input, voltage controlled
- Soft swithcing FWD Technology
- Package with copper base plate
- Isolation voltage 4000V

Application

- AC and DC motor control
- AC servo and robot drives
- power supplies
- welding inverters

Advantages

- space and weight savings
- reduced protection circuits

SGO400NF120UC3

IGBT Modules

Characteristics

T_C = 25°C, unless otherwise specified

Symbol	Conditions	min.	typ.	max.	Units
IGBT					
V _{GE(th)}	V _{GE} = V _{CE} , I _C = 15.2mA	4.5	5.0	5.7	V
I _{CES}	V _{GE} = 0; V _{CE} = V _{CES} ; T _J = 25°C			0.5	mA
V _{CE(TO)}	T _J = 25°C		1.4	1.6	V
r _{CE}	V _{GE} = 15V, T _J = 25(150)°C		2.75 (3.75)	3.51(4.75)	mΩ
V _{CE(sat)}	I _C = 400A; V _{GE} = 15V; chip level		2.30	2.55	V
C _{ies}	under following conditions V _{GE} = 0, V _{CE} = 25V, f = 1MHz		28.8		nF
C _{oes}			4.40		
C _{res}			2.52		
L _{CE}				30	nH
R _{CC'+EE'}	res., terminal-chip T _C = 25(125)°C		0.35(0.55)		mΩ
t _{d(on)}	under following conditions: V _{CC} = 600V, I _C = 400A R _{Gon} = R _{Goff} = 10Ω, T _J = 125°C V _{GE} = ± 15V		25		ns
t _r			49		ns
t _{d(off)}			290		ns
t _f			88		ns
E _{on} (E _{off})	T _C = 25°C		70(25)		mJ
Inverse Diode under following conditions:					
V _F = V _{EC}	I _F = 400A; V _{GE} = 0V; T _J = 25°C		2.20	2.52	V
V _(FO)	T _J = 25(150)°C		1.3(0.9)	1.5(1.1)	V
r _F	T _J = 25(150)°C		2.3(3.1)	2.5(3.4)	mΩ
I _{RRM}	I _F = 400A; T _J = 150°C		450		A
Q _{rr}	di/dt = 8800A/us		68		uC
E _{rr}	V _{GE} = 15V		30		mJ
Thermal Characteristics					
R _{th(j-c)}	per IGBT			0.072	K/W
R _{th(j-c)D}	per Inverse Diode			0.140	K/W
R _{th(c-s)}	per module			0.038	K/W
Mechanical Data					
M _s	to heatsink M6	3		5	Nm
M _t	to terminals M6	2.5		5	Nm
Weight	typical			340	g

SGO400NF120UC3

IGBT Modules

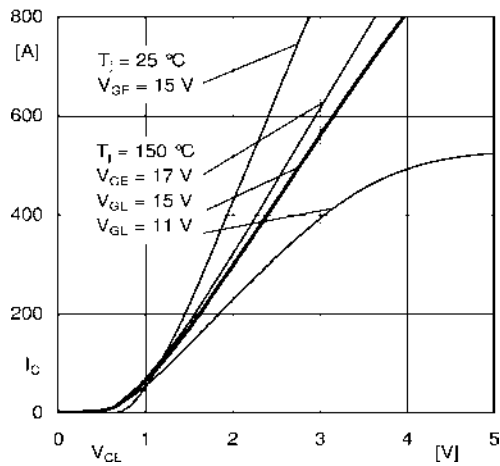


Fig. 1: Typ. output characteristic, inclusive $R_{CC} + E_{E'}$

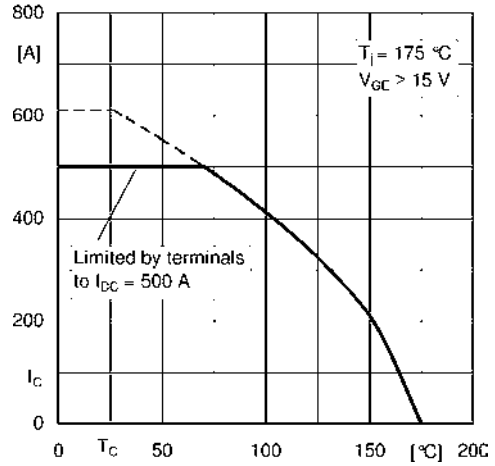


Fig. 2: Rated current vs. temperature $I_C = f(T_C)$

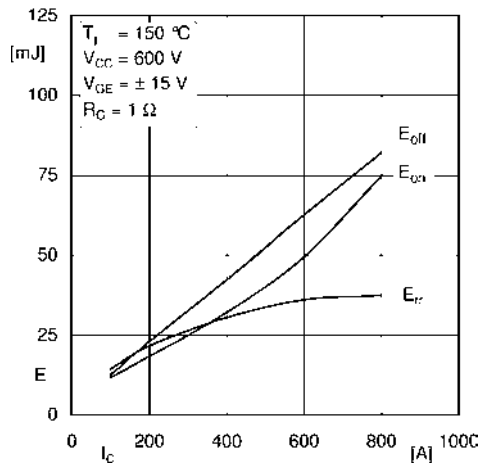


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

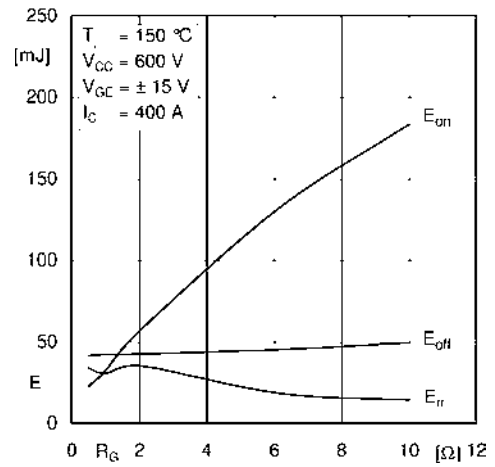


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

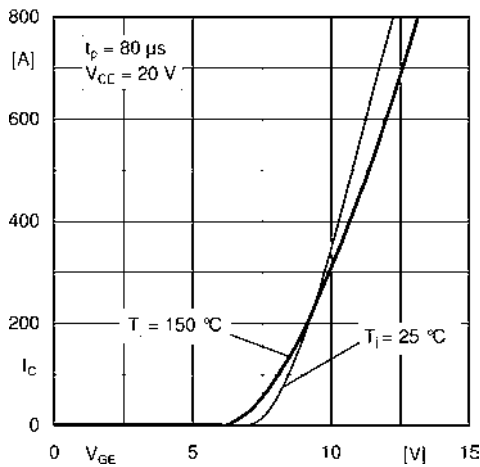


Fig. 5: Typ. transfer characteristic

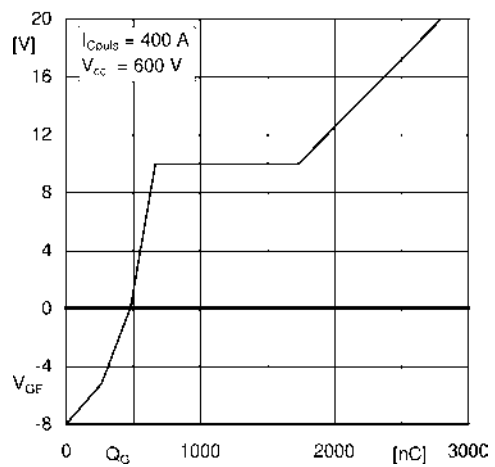


Fig. 6: Typ. gate charge characteristic

SGO400NF120UC3

IGBT Modules

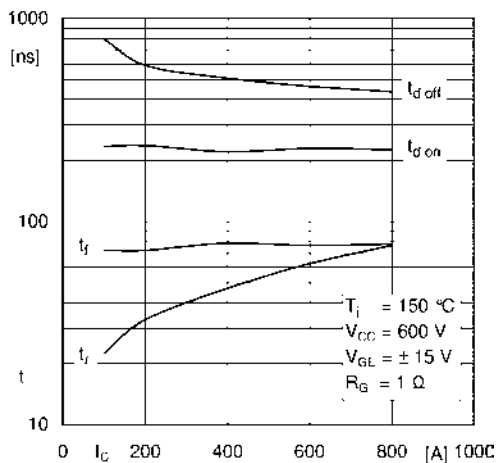


Fig. 7: Typ. switching times vs. I_C

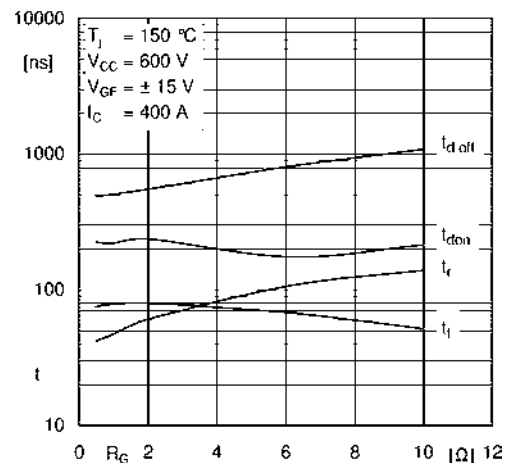


Fig. 8: Typ. switching times vs. gate resistor R_G

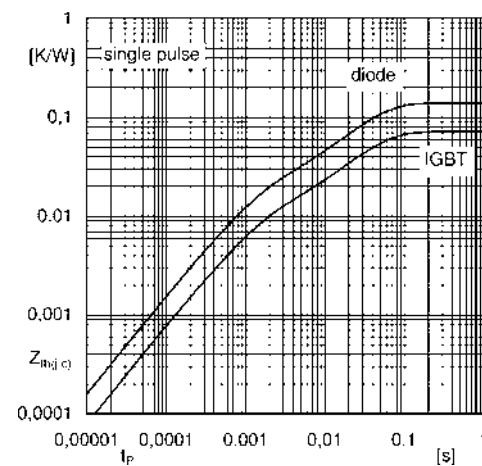


Fig. 9: Transient thermal impedance

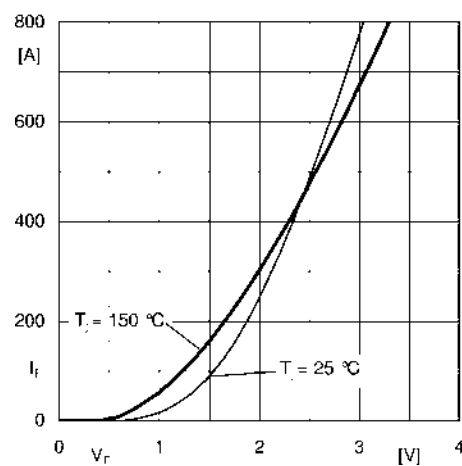


Fig. 10: Typ. FRD diode forward charact., incl. $R_{CC}+EE'$

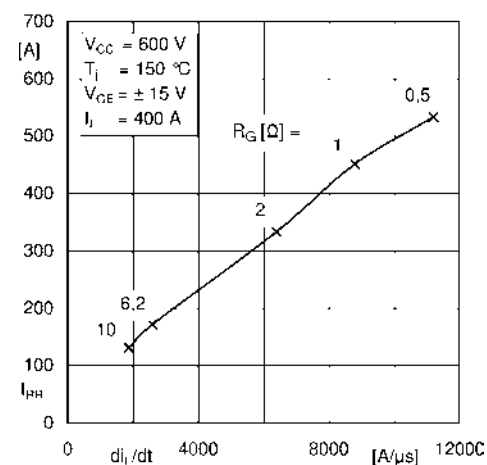


Fig. 11: FRD diode peak reverse recovery current

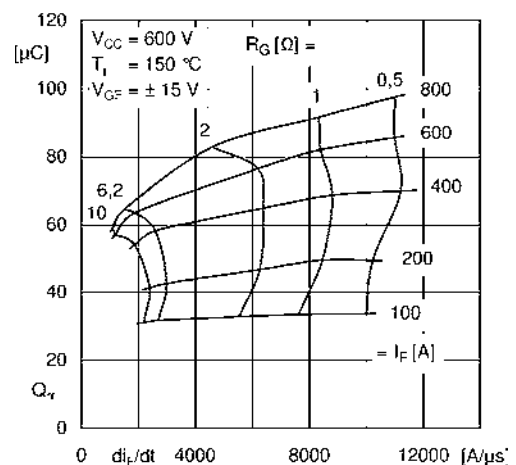


Fig. 12: Typ. FRD diode peak reverse recovery charge